



STAUF D 70

Very low emission tile slip stop











	Technical Datasheet
Product number	✓ 141080
Special features	tiles can be exchangedtile slip stop
Application range	✓ slip stop for self-laying carpet tiles
Suitable for installation of	✓ Self laying carpet tiles
Suitable sub floors	 calcium sulphate (flow) floors Raised access floors wooden planks, solid wood fibre boards STAUF levelling compounds chipboards V100 (E1), OSB boards unlaminated gypsum fibre boards cement floors
Suitable levelling compounds	 ✓ STAUF SPP 95 ✓ STAUF AS ✓ STAUF ES ✓ STAUF GS ✓ STAUF GS-Stand ✓ STAUF FZ ✓ STAUF OS ✓ STAUF RM ✓ STAUF SSP RAPID
Product properties	 permanently sticky adhesive film in homes suitable for sub floor heating systems easy to roll out very economical low viscosity
Color	✓ white
Required quantities per m²	√ 75g when applied with roller

Open time	✓ 60 - 80 minutes at 20 °C
Flash time	√ 15 - 30 minutes
Accessibility	✓ immediately
Room climate at work site	minimum 15 °C, maximum 75% rel. humidity, preferably max. 65%
Transport requirements	✓ frost-free
Storage requirements	✓ frost-free
Shelf-life	✓ 9 months
Giscode	✓ D1
Emicode	✓ EC1 plus
Available packaging	✓ 10 kg plastic canister



EXAMINATION OF SUB FLOOR

Prior to processing, the sub floor must be checked according to the standard DIN 18365 or corresponding national standards (e.g. BS 5325). The sub floor shall be resistant to pressure and tension, free of cracks, must have sufficient surface strength, be permanently dry, level, clean and free of anti-adherents, sinter layers etc. In addition, porosity and grip of surface need to be checked. Also check moisture content and absorptive capacity of cement (flow) and calciumsulfate (flow) floors as well as room temperature, air humidity and sub floor temperature.



SUB FLOOR PREPARATION

It must be ensured that the sub floor is ready for installation by performing proper sub floor preparation, floors must be clean, have sufficient surface strength, must be level, permanently dry and free of cracks. A mechanical pretreatment of the subfloor (sweeping, vacuuming, mechanical brushing, sanding, milling, shot blasting) must be performed depending on type and condition of sub floor. Cracks and joints, except expansion joints and other construction joints, shall be solidly closed with STAUF casting resin and floor brackets. Cavities and indentations can be filled with a non self-levelling STAUF levelling compound. Before installing floor coverings, the properly prepared sub floors must normally be levelled using the appropriate STAUF levelling compound. Once sub floors have been levelled, do not apply primers.



PROCESSING

Apply adhesive evenly on sub floor using appropriate roller. Let adhesive dry until adhesive layers become transparent (15-30 minutes). The higher the applied quantity, the better the adhesion. After specified flash-time and after the adhesive film has become transparent, install floor covering during open time and press down or rub down firmly. With regard to installation, always observe manufacturer\'s instructions.

LIMITATION OF LIABILITY



The foregoing representations are based on the results of our most current product and material testing and are of a non-obligatory advisory nature only since we have no control over the actual quality of workmanship, materials used and worksite conditions. As such, they do not constitute an express or implied warranty of any kind. The same applies to our commercial and technical consultation services which are provided free-of-charge and without obligation. Therefore, we strongly recommend that prior onsite testing be conducted to observe and study the suitability of the product for the intended purpose. With the release of this technical information, all prior technical information (technical data sheets, installation recommendations and other information regarding similar purposes) becomes invalid.

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